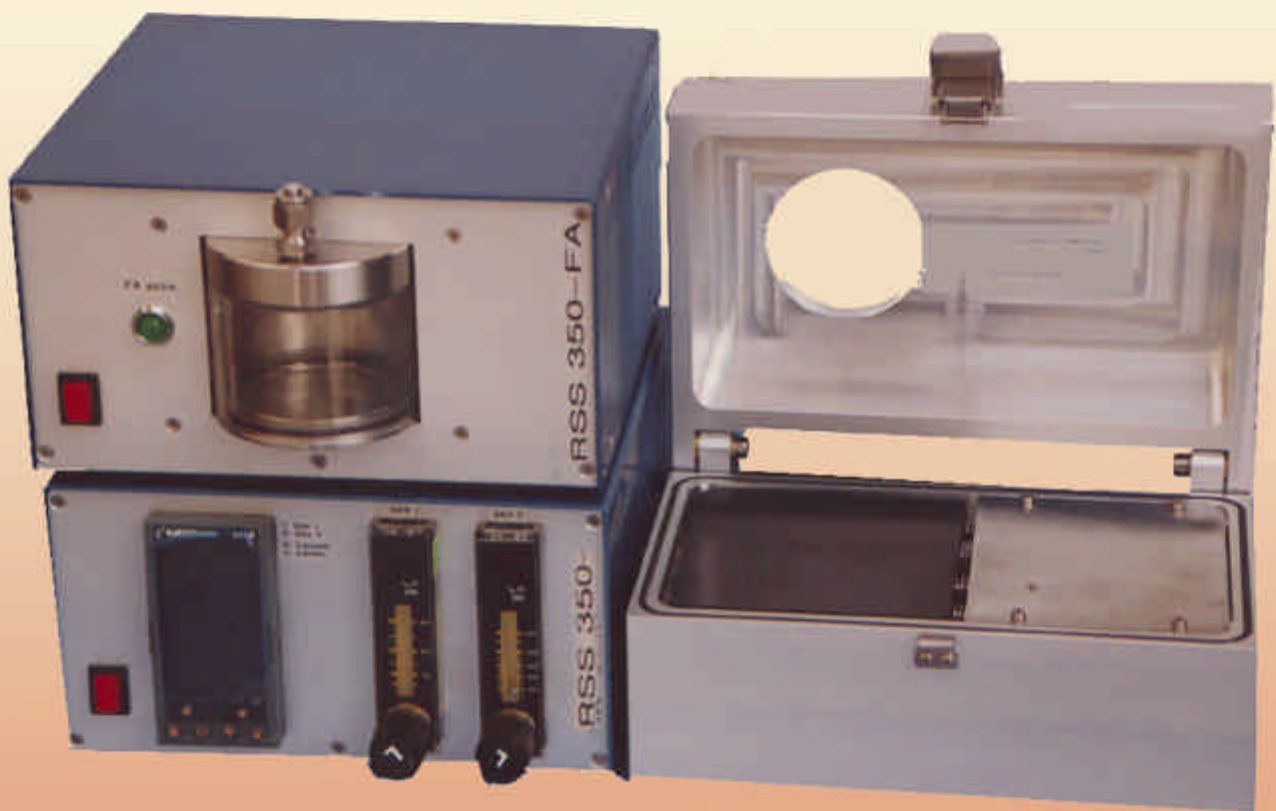


Mini Reflow Solder System Modell RSS 350



- Perfect solder results
- fluxless and voidfree soldering
- in vacuum or inert gas atmosphere

Reflow Solder System

Model RSS 350

- flux free soldering
- programmable temperature profiles
- record of the process data
- Windows based Software
- 1 program with 16 segments saveable
- process in gas or vacuum
- small place requirements

The **Reflow Solder System RSS-350** is developed for small budget and space purposes. The system has one separate chamber and an external process controller. It is an excellent tool for various solder processes and other applications. Some applications are: as laboratory hot plate for all kind of developers implementing and researching new processes, e.g. flux less soldering, flip-chip process, adhesive bonding, hermetic sealing under controlled atmospheres, solder bump reflowing, encapsulation of housings, soldering of power devices, heat treatment of semiconductor wafers, prototype research, quality control, environmental research purposes and for small pre-series or series.

The chamber is hermetically sealed with a viewing window which allows observation of the process during soldering. The heated surface is 110 mm x 110 mm.

Two program controlled gas lines (one gas line is standard) with flow meters allow the usage of two different gases, either Nitrogen (enriched with Formic Acid for flux less soldering) or forming gas. By connecting an external pump makes the furnace vacuum capable up to 10^{-3} mbar.

Key features are precise controlled fast ramp-up and ramp-down rates which are **better 120°C/minute for ramp-up** and a **ramp down rate of better 100°C/minute**. These steps are programmable from **room temperature up to a maximum of 350°C**.

The process is programmed by an external controller which is provided with software. You can control the process either directly at the controller (there is a display showing the status) or by using the RS-232 interface connected with a standard PC. This allows storing of unlimited programs where all temperature profiles with segments can be saved. An additional feature is the choice between precisely programming the ramp-rate or the ramp-to-target.

This tool is a low cost solution for various applications and customers. A further advantage is the small size of the chamber (240mm x 200mm x 150mm) and the controller (220mm x 220mm x 125mm). The small system can be easily transported from one place to the other (the chamber weighs only 8 kg and the controller 3 kg) which simplifies lab use.

RSS3650 Technical Data

Heated area:	110mm x 100mm
Temperature Range:	up to 350°C
Voltage:	240V, 50 Hz (120V, 60 Hz)
Power Supply:	1600W (115V: 1200W)
Vacuum:	up to 10^{-3} mbar
Programs:	one program with max. 16 segments storable (unlimited segments storable with PC)
Ramp up rate:	better 120°C/Minute
Ramp down rate:	better 100°C/Minute
Interface:	RS232 incl. PC Controller Software
Chamber top:	with viewing window to observe process
Dimensions:	process chamber: 240x200x150mm External control.: 220x220x125mm
Weight:	process chamber: 8 kg External control.: 3 kg

Options and Accessories :

RSS-350-FA	Formic Acid Module – highly recommended for flux less soldering
RSS-350-FM	Additional gas line with flow meter
RSS-350-MPC	Chemical resistant Membrane (Diaphragm) Pump
RSS-350-WC	Closed loop water cooling system